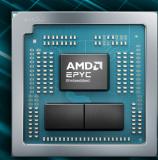
# PRODUCT BRIEF AMD EPYC™ EMBEDDED 2005 SERIES PROCESSOR





The rapid rise of AI is placing unprecedented demand on networking, storage, and industrial edge infrastructure. Organizations are struggling to keep pace with workloads that require more compute power, faster memory, and higher I/O performance, while also balancing limited space, strict power budgets, and long lifecycle requirements. At the same time, the industry shift from DDR4 to DDR5 is accelerating change, creating new opportunities for system redesign. The AMD EPYC™ Embedded 2005 processor is built to address these challenges.

## PRODUCT OVERVIEW

The EPYC Embedded 2005 Series is a next-generation mid-tier x86 embedded BGA processor from AMD designed for high-performance networking, storage, and industrial applications that demand enterprise-class reliability within tight thermal and mechanical envelopes.

Built on advanced 4nm (CCD) + 6nm (IOD) process technology, it integrates up to 16 "Zen 5" CPU cores, dual-channel DDR5-5600 memory, and 28 lanes of PCle® Gen5 in a compact 40mm×40mm BGA package, delivering exceptional performance-per-watt across embedded deployments.

It also features 64 MB of shared L3 cache for high compute density and energy efficiency and is up to 2.4x smaller<sup>1</sup> than comparable, competing Enterprise BGA solutions. The device achieves up to 35% higher Base CPU frequencies at half the power of the competition<sup>2</sup>, enabling designers to reduce system costs while maximizing performance and efficiency.

Engineered for power-, thermal-, and space-constrained deployments, the EPYC™ Embedded 2005 processor delivers reliable, low-latency performance for networking, storage, and industrial edge systems that must operate continuously for up to 10 years. With dozens of advanced RAS features and robust hardware-based security, it ensures maximum up-time and data protection in demanding, always-on environments.

AMD EPYC™ Embedded 2005 processors deliver leading I/O throughput for flexible, high-bandwidth expansion and scalable system design. Paired with DDR5 memory support, it provides a future-ready platform offering faster data transfer, broader connectivity options, and extended product longevity.

## **PRODUCT HIGHLIGHTS**

- Superior performance-per-watt to optimize system BOM cost
- Enables system cost efficiency through adjustable 45–75W TDP and compact BGA packaging
- Offers up to 10 years of field operation with enterprise-grade reliability (RAS) for 24/7 'always on' systems

## TARGET MARKETS AND APPLICATIONS

#### **NETWORKING**

- Control planes
- Routers
- Switches
- · Security appliances

#### **STORAGE**

- · Cold cloud storage
- EBOD (Extended Bunch of Disks)

#### INDUSTRIAL

- Robotics
- Machine control
- · Real-time industrial operations

### **AEROSPACE & DEFENSE**

· Ruggedized embedded systems



## **KEY FEATURES**

CATEGORY	HIGHLIGHTS		
CPU	• Up to 16x Zen 5 cores / 32 threads, 1MB L2 per core, up to 64MB L3 cache shared		
MEMORY	• 128b DDR5-5600 with sideband ECC		
1/0	• 28 PCIe Gen5 lanes, 11 root ports, NVMe, enhanced hot-plug		
CONNECTIVITY	• 4× USB 3.2 Gen2 + 1× USB 2.0, 1x SPI/eSPI, 1x SPI, 4× I2C/I3C		
POWER ENVELOPE	Configurable 45–75W cTDP		
PACKAGE	• Lidless 40×40mm BGA, 0.81mm pitch, 1,763 balls		
RELIABILITY	• Enterprise-class RAS features and up to 10-year field operation		
SOFTWARE	• EDKII, Yocto, Upstreamed Linux® Kernel drivers		

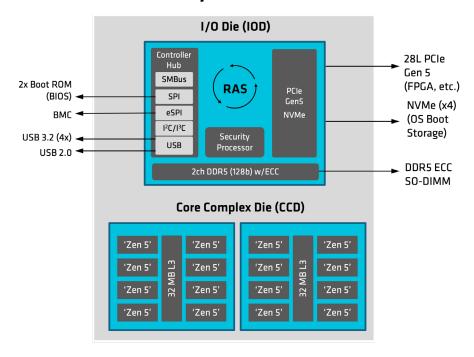
## AMD EPYC™ EMBEDDED 2005 SERIES PROCESSOR PRODUCT TABLE

	Model #	2435	2655	2875	
	OPN	100-000001912	100-000001911	100-000001910	
	Die Configuration	1 CCD + 1 IOD	1 CCD + 1 IOD	2 CCD + 1 IOD	
Compute	"Zen 5" Cores	8	12	16	
	# of Threads	16 Threads	24 Threads	32 Threads	
	L3 Shared Cache	32 MB	64 MB	64 MB	
	Base <sup>1</sup> / Boost Frequency	2.8 / 4.5 GHz	2.7 / 4.5 GHz	3.0 / 4.5 GHz	
1/0	PCIe° Gen5	28 Lanes   11 Root Ports   SR-IOV   Enhanced Hot Plug			
	Storage Interface	4x NVMe			
	DDR Interface	2-Channel DDR5-5600 (1 DIMM/Channel) or DDR5-3600 (2 DIMMs/ch) w/sideband ECC			
	USB	4x USB 3.2 Gen 2 (10 Gb/s) + 1x USB 2.0 (480 Mb/s)			
	SPI	1x eSPI/SPI Controller + 1x SPI Controller			
	12C / 13C	4x ports (SMBus: 2x Ports Shared with I2C)			
Power & Thermal	cTDP	45-55W	45-75W	45-75W	
	Nominal TDP	45W	55W	75W	
	Junction Temperature	0 to 105°C	0 to 105°C	0 to 105°C	
Package & Longevity	Package	FL1 Lidless BGA: 40 x 40 x 2.133 mm; 0.81 mm pitch, 1,763 ball count			
	Planned Availability	Up to 10 Years			

CPU base frequency attainment at nominal TDP is characterized within a 0 to 95°C Tj range

## **4nm Chiplet Architecture**





## **VALUE PROPOSITION**

- Superior perf/W and balanced I/O density to optimize system BOM cost
- Enterprise reliability for mission-critical embedded deployments.
- Cost-optimized design with flexible thermal options
- Future-ready platform with 10-year manufacturing longevity and DDR5 support an ideal upgrade from DDR4
- Diversified supply chain opportunity for OEMs seeking alternatives from competitors

## **SUMMARY**

AMD EPYC Embedded 2005 Series processor redefines performance, power efficiency, and reliability for embedded x86 systems. With its small footprint, enterprise-class RAS, and scalable architecture, it empowers OEMs to deliver next-gen networking, storage and industrial solutions that are powerful, efficient, and future-ready — all while reducing cost.

#### **FOOTNOTES**

- 1. EE2-003: AMD EPYC™ Embedded 2005 Series processor is 2.4x smaller than Intel Xeon™ 6500P-B Series.
  - Based on AMD internal analysis as of November 2025. AMD EPYC<sup>TM</sup> Embedded 2005 Series has a 40mm x 40mm (1,600mm2) BGA package size. Intel Xeon McG00P-B Series has a 77.5mm x 50mm (3,875mm2) BGA package size. (3,875mm2 1,600mm2) / 1,600 mm2 = 142% smaller package area or 2.42x smaller Intel Xeon 6500P-B Processor specifications: https://www.intel.com/content/www/us/en/products/details/processors/xeon/edge.html
- 2. EE2-004: AMD EPYC™ Embedded 2655 model processor delivers up to 35% higher Base CPU frequency at half of the TDP (Thermal Dissipation Power) of Intel Intel Xeon™ 6503P-B.
  - Based on AMD internal analysis as of November 2025. AMD EPYC™ Embedded 2655 is a 12-core "Zen 5" processor model with a 2.7 GHz Base CPU frequency and 55W nominal TDP. Intel Xeon™ 6503P-B is a 12-core processor model with a 2.0 GHz Base CPU frequency and 110W nominal TDP. (2.7 GHz 2.0 GHz) / 2.0 GHz = 35% higher Base CPU frequency or 1.35x better. (110W 55W) / 100W = 0.5x or half the TDP. Intel Xeon™ 6503P-B specifications: <a href="https://www.intel.com/content/www/us/en/products/sku/242897/intel-xeon-6503pb-processor-48m-cache-2-00-ghz/specifications.html">https://www.intel.com/content/www/us/en/products/sku/242897/intel-xeon-6503pb-processor-48m-cache-2-00-ghz/specifications.html</a>

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